

**AMENDMENTS TO THE SPECIFICATION**

Please replace the third full paragraph on page 9, with the following amended paragraph.

No new matter is added.

~~Among them~~ Among them, the liquid cleaner of the present invention is useful to silicon wafer, glass substrate for LCD and PDP and compound semiconductor substrate of such as GaAs and GaP, in particular, to silicon wafer and compound semiconductor of such as GaAs and GaP. Further, the liquid cleaner of the present invention is useful to, among these substrates, substrate on which surface metal wiring is provided, such as copper, silver, aluminum, tungsten plug, chromium, gold, and the like, and in particular, to substrate on which surface copper or silver wiring is provided or further substrate on which surface copper wiring is provided and is most useful to semiconductor substrate on which copper wiring is provided